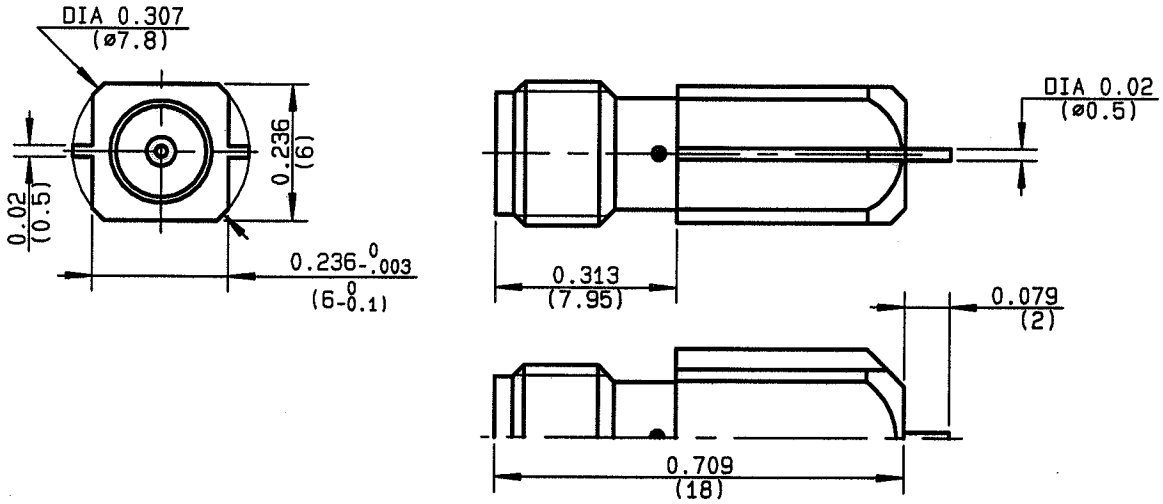


**STRAIGHT JACK RECEPTACLE SMT  
EDGE CARD TYPE**

**R124.423.033**  
SERIES SMA B



NOMINAL IMPEDANCE	<b>50</b> Ω
FREQUENCY RANGE	<b>0-18</b> GHz
TEMPERATURE RATING	<b>-65/+105</b> °C
V.S.W.R	<b>1.05 + .05 x F(GHz)</b> Maxi
RF INSERTION LOSS	<b>.05</b> √F(GHz) dB Maxi
VOLTAGE RATING	<b>500</b> V <sub>eff</sub> Maxi
DIELECTRIC WITHSTANDING VOLTAGE	<b>1000</b> V <sub>eff</sub> Mini
INSULATION RESISTANCE	<b>5000</b> MΩMini
HERMETIC SEAL	<b>NA</b> Atm.cm <sup>3</sup> /s
PACKAGE (pressurized only)	<b>NA</b>
MECHANICAL DURABILITY	<b>100</b> Cycles
WEIGHT	<b>3.07</b> gr
SPECIFICATION	

CABLES :

OTHERS CHARACTERISTICS

UNIT PACKAGING

CABLE RETENTION	<b>NA</b>	N Mini
CENTER CONTACT RETENTION		
Axial force - mating end	<b>15</b>	N Mini
Axial force - opposite end	<b>15</b>	N Mini
Torque	<b>0.5</b>	cm.N Mini
RECOMMENDED TORQUES		
Mating	<b>40</b>	cm.N
Panel nut	<b>NA</b>	cm.N
Clamp nut	<b>NA</b>	cm.N

CONNECTOR PARTS:	MATERIALS	FINISH	(all values are given in micrometers)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2	
OUTER CONTACT			
CENTER CONTACT	BERYLLIUM COPPER	GOLD 1.3 OVER COPPER 2.5	
INSULATOR	PTFE	-	
GASKET		-	
OTHERS PIECES			

FANJA

ISSUE	CREATION DATE	FILE PART-NUMBER
<b>9811B00</b>	<b>16-JAN-97</b>	<b>96-0019-025</b>



**RADIALL®**

The information given here is subject to change without notice. Design changes may be in order to improve the product.

Connect to the future



**R124.423.033**

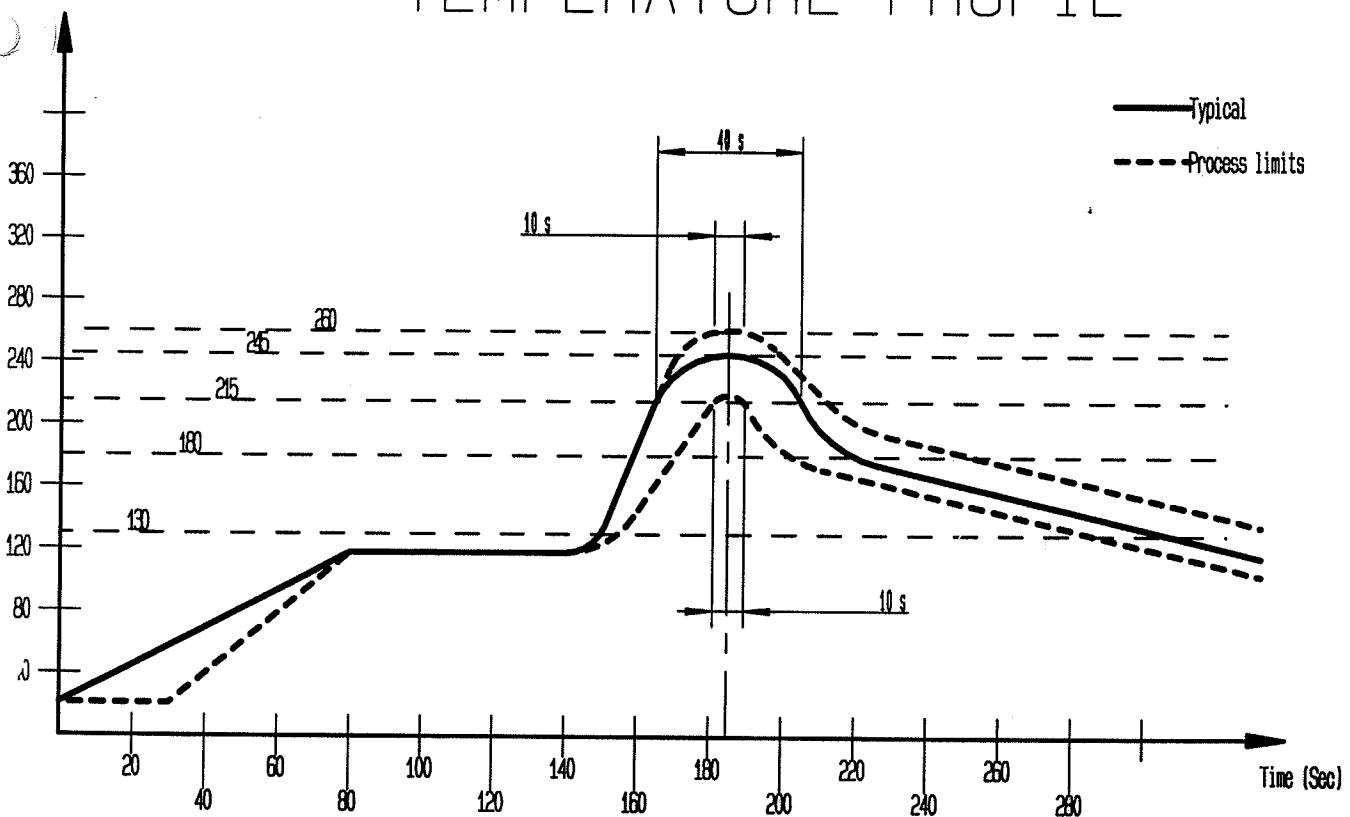
ISSUE **9811B00** SERIES **SMA B**

## SOLDER PROCEDURE

- 1 - Deposit solder paste "Sn63Pb35Ag2" on mounting zone by screen printing application. We recommend a low Residue Solid flux.  
We advise a thickness of 200 micromm (7.800 microinch). Verify that the edges of the zone are clean.
- 2 - Placement of the receptacle on the mounting zone with an automatic machine of "pick and place" type. Aspiration port (see page 3/3) centered into body and push against it.  
Video camera is preferred to check the positioning of the component. (See page 3)  
Adhesive agents are forbidden on the receptacle.
- 3 - Soldering by infra-red reflow.  
We give under, the typical profile to use.
- 4 - Cleaning of printed circuit boards .
- 5 - Checking of solder joints and position of the component by visual inspection.

Temperature (Degre C)

## TEMPERATURE PROFIL



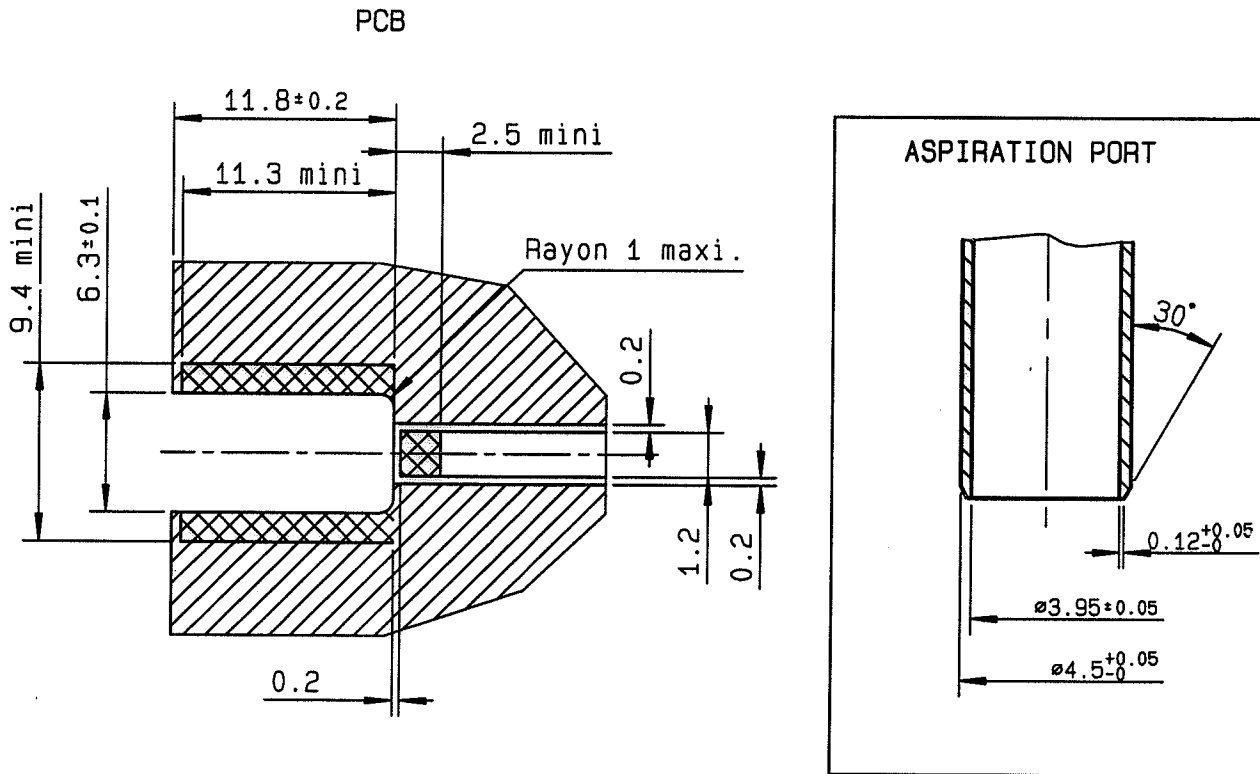


**RADIALL®**

**R124.423.033**

ISSUE **9811B00**

SERIES  
**SMA B**



**COPLANAR LINE**

Pattern and signal are on the same side  
Thickness of PCB : .063 (1.6 mm)  
The material of PCB is the epoxy resin  
of glass fabrics baos. (Er = 4.8)  
The solder resist should be printed  
except for the land pattern on the PCB.

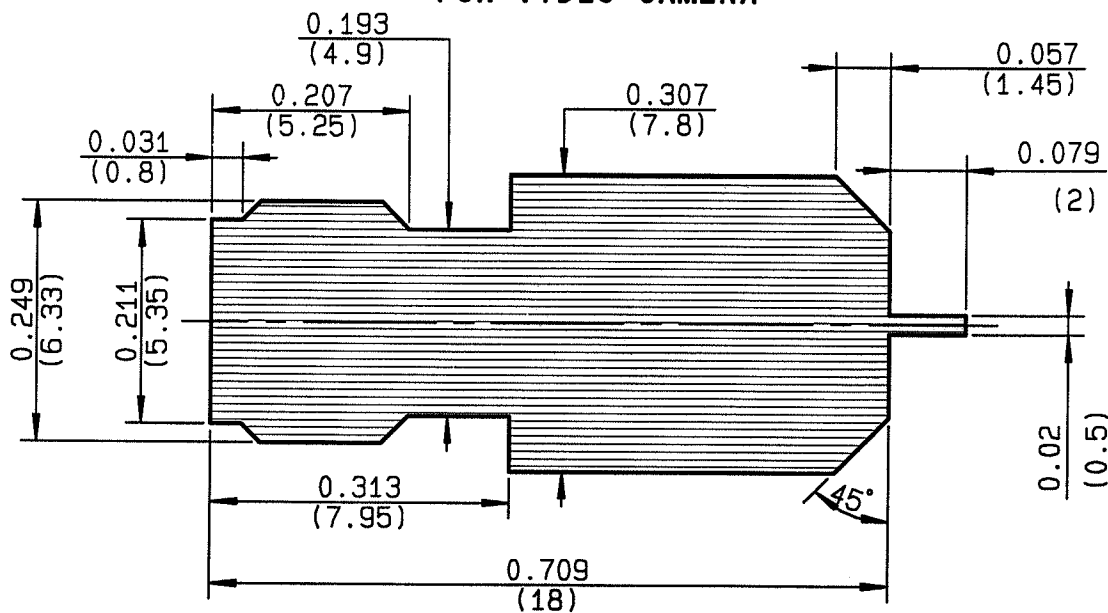


Pattern



Land for solder paste

**SHADOW OF MCX RECEPTACLE  
FOR VIDEO CAMERA**



FANJAT